

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2818
shw
B

Applicant: Cheng-Yi Liu et al.

Title: THINNED DIE INTEGRATED CIRCUIT PACKAGE

Docket No.: 884.793US1

Filed: January 7, 2002

Examiner: Mai-Huong Tran

Serial No.: 10/036389

Due Date: May 18, 2004

Group Art Unit: 2818



Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 CFR 1.111 (9 Pages).
- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$172.00 to cover the fee for additional claims as calculated below.

If not provided for in a separate paper filed herewith, If an additional fee is required due to changes to the claims, the fee has been calculated as follows:

CLAIMS AS AMENDED						
	(1) Claims Remaining After Amendment		(2) Highest Number Previously Paid For	(3) Present Extra	Rate	Fee
TOTAL CLAIMS	30	-	31	0	x 18.00 =	\$0.00
INDEPENDENT CLAIMS	5	-	3	2	x 86.00 =	\$172.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED						\$0.00
TOTAL						\$172.00

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: *Ann M. McCrackin*
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 18th day of May, 2004.

KACIA LEE
Name

Kacio Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/036389

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Yi Liu et al.

Examiner: Mai-Huong Tran

Serial No.: 10/036389

Group Art Unit: 2818

Filed: January 7, 2002

Docket No.: 884.793US1

Title: THINNED DIE INTEGRATED CIRCUIT PACKAGE

Assignee: Intel Corporation

Customer No: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on February 18, 2004. Please amend the above-identified patent application as follows.

05/24/2004 JBR/LINAN 00000085 190743 10036389
01 FC:1201 172.00 DA